

ABSTRACT

An integrated circuit (IC) package includes a mold compound, a die, and a window. The mold compound has a frame embedded within it. The frame has a top surface, a bottom surface, and a top-to-bottom opening therein. The die is attached to the mold compound, wherein the embedded frame lies below a periphery of the die. The window is attached to the mold compound and located above the die to allow light to reach the die.